

### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

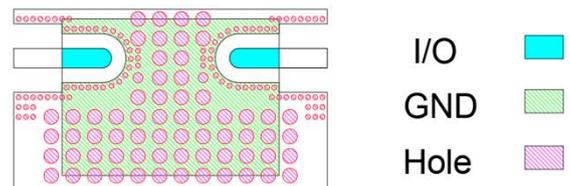
NO.	Parameter	SPEC
1	Frequency range	7610-7630 MHz
2	Insertion Loss	3.2dB max. at +25°C;
3	Ripple	0.5dB
4	Attenuation	60 dB min. @ DC-6000MHz 30 dB min. @ 9300MHz 50 dB min. @10000-16000MHz
5	VSWR (In BW)	2.0 max.
6	Port Impedance	50Ω
7	Power	0.5W max.
8	Operation Temperature Range	-55°C ~ +100°C

### Construction



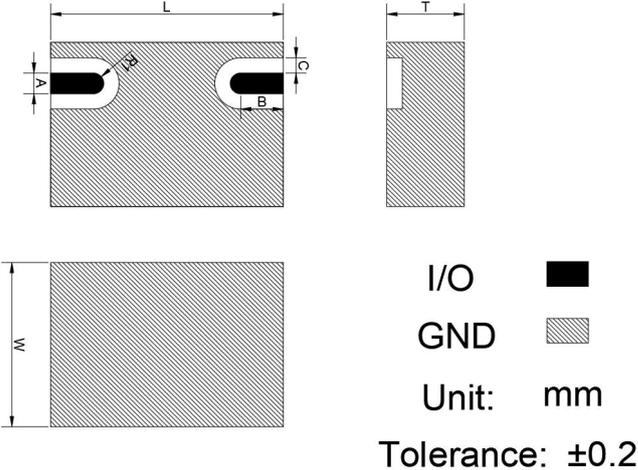
PIN	Connection
1	Input port
2	Output port
3	GND

### Mounting Considerations

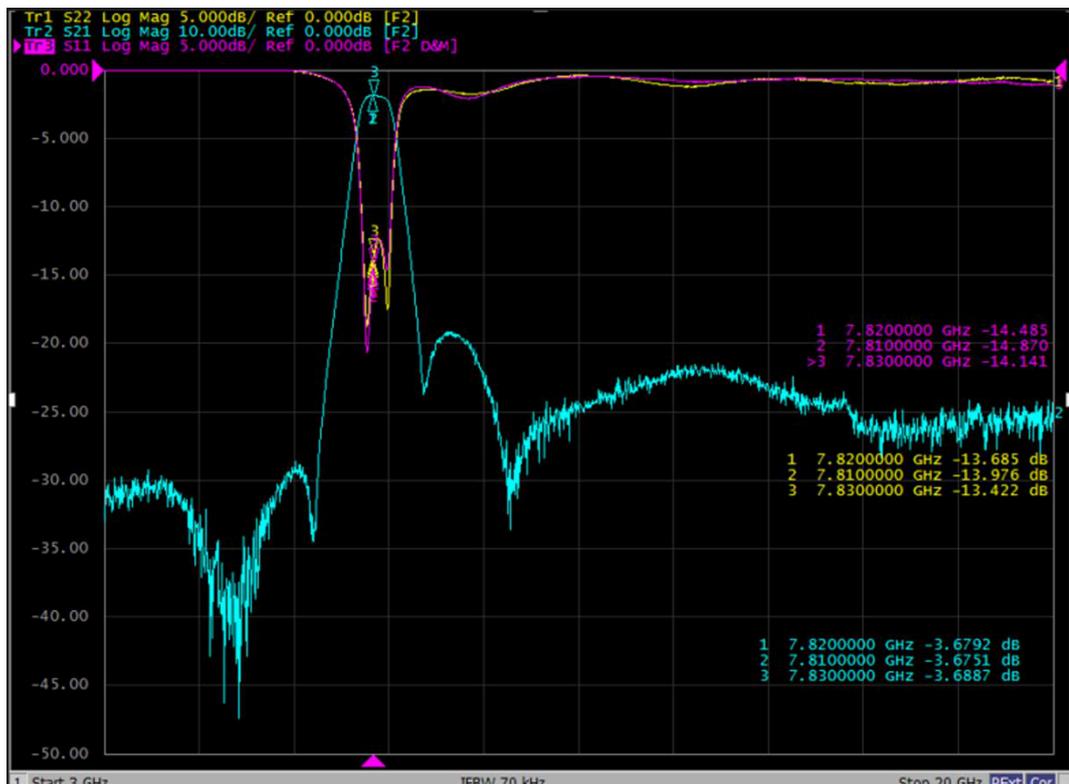


Unit: mm  
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

### Dimensions

Figure	Symbol	Dimension (mm)
 <p>Unit: mm Tolerance: <math>\pm 0.2</math></p>	L	$4.5 \pm 0.20$
	W	$3.2 \pm 0.20$
	T	$1.5 \pm 0.20$
	A	$0.4 \pm 0.10$
	B	$0.83 \pm 0.10$
	C	$0.3 \pm 0.10$
	R1	$0.2 \pm 0.10$

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.